

Designing-In Light Curing Adhesives for Medical Device Assembly

Will you be at the [Med-Tech Innovation Expo](#) this year? The show, which runs from 28-29 September 2021 at the NEC in Birmingham, will feature a short seminar from our Managing Director, Peter Swanson. ***Designing-in Light Curing Adhesives for Medical Device Assembly*** will present an overview of UV and visible light curing adhesives and what medical device designers should be considering at the design stage to take full advantage of the benefits of this technology, including productivity potential. [Adhesives, coatings and protective materials which cure with light](#) can offer significant process as well as functional improvements to an assembly. Come hear how this technology works, what recent advances can help improve productivity, and example applications.

If you would like to speak to us about your specific application, the particular adhesives, coatings and sealants we can offer, or check out our robotic dispensing and UV light curing systems, our team would be pleased to see you at our stand.

Designing-In Light Curing Adhesives for Medical Device Assembly



Peter will present *Designing-In Light Curing Adhesives for Medical Device Assembly* at 11:20 a.m. on 29 September, on the Introducing Stage. Our stand is just a few down from the stage, at A24.

If you haven't already registered for the Med-Tech Innovation Expo, you can [sign up here for free entry](#). We hope to see you there!

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